

PMN20EN

30 V, 6.7 A N-channel Trench MOSFET

Rev. 1 — 30 May 2011

Product data sheet

1. Product profile

1.1 General description

N-channel enhancement mode Field-Effect Transistor (FET) in a small SOT457 (SC-74) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

1.2 Features and benefits

- Logic-level compatible
- Very fast switching
- Trench MOSFET technology

1.3 Applications

- Relay driver
- High-speed line driver
- Low-side loadswitch
- Switching circuits

1.4 Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|----------------------------------|--|-----|-----|-----|------------|
| V_{DS} | drain-source voltage | $T_j = 25\text{ }^\circ\text{C}$ | - | - | 30 | V |
| V_{GS} | gate-source voltage | | -20 | - | 20 | V |
| I_D | drain current | $V_{GS} = 10\text{ V}; T_{amb} = 25\text{ }^\circ\text{C}$ | [1] | - | 6.7 | A |
| Static characteristics | | | | | | |
| $R_{DS(on)}$ | drain-source on-state resistance | $V_{GS} = 10\text{ V}; I_D = 6.7\text{ A}; T_j = 25\text{ }^\circ\text{C}$ | - | 16 | 20 | m Ω |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm².

2. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------|-----------------------|----------------|
| 1 | D | drain | <p>SOT457 (TSOP6)</p> | <p>mbb076</p> |
| 2 | D | drain | | |
| 3 | G | gate | | |
| 4 | S | source | | |
| 5 | D | drain | | |
| 6 | D | drain | | |



3. Ordering information

Table 3. Ordering information

| Type number | Package | | Version |
|-------------|---------|--|---------|
| | Name | Description | |
| PMN20EN | TSOP6 | plastic surface-mounted package (TSOP6); 6 leads | SOT457 |

4. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PMN20EN | SK |

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

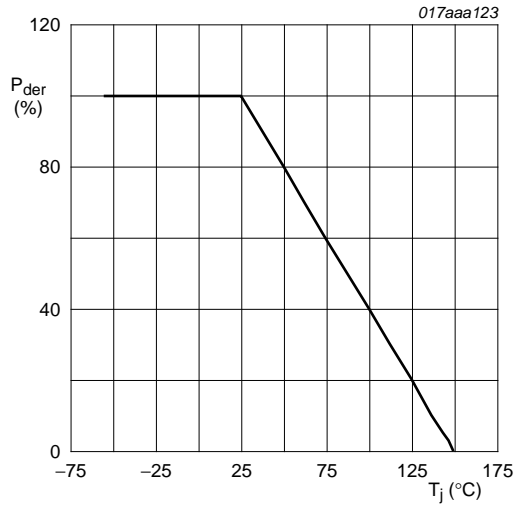
| Symbol | Parameter | Conditions | Min | Max | Unit | |
|-----------|-------------------------|--|-----|-----|------|----|
| V_{DS} | drain-source voltage | $T_j = 25\text{ °C}$ | - | 30 | V | |
| V_{GS} | gate-source voltage | | -20 | 20 | V | |
| I_D | drain current | $V_{GS} = 10\text{ V}; T_{amb} = 25\text{ °C}$ | [1] | - | 6.7 | A |
| | | $V_{GS} = 10\text{ V}; T_{amb} = 100\text{ °C}$ | [1] | - | 4.5 | A |
| I_{DM} | peak drain current | $T_{amb} = 25\text{ °C};$ single pulse; $t_p \leq 10\text{ }\mu\text{s}$ | - | 27 | A | |
| P_{tot} | total power dissipation | $T_{amb} = 25\text{ °C}$ | [2] | - | 545 | mW |
| | | | [1] | - | 1390 | mW |
| | | $T_{sp} = 25\text{ °C}$ | | - | 4170 | mW |
| T_j | junction temperature | | -55 | 150 | °C | |
| T_{amb} | ambient temperature | | -55 | 150 | °C | |
| T_{stg} | storage temperature | | -65 | 150 | °C | |

Source-drain diode

| | | | | | | |
|-------|----------------|--------------------------|-----|---|-----|---|
| I_S | source current | $T_{amb} = 25\text{ °C}$ | [1] | - | 1.2 | A |
|-------|----------------|--------------------------|-----|---|-----|---|

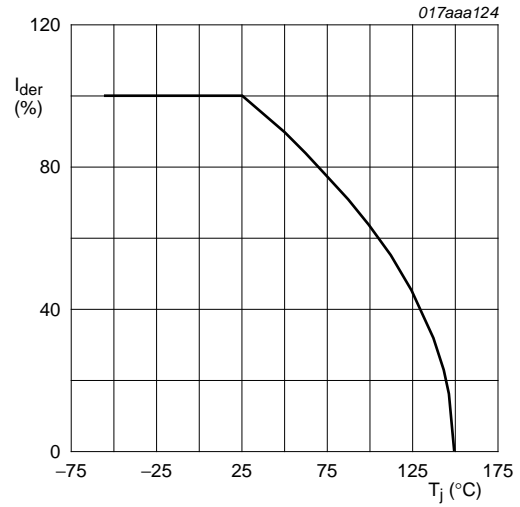
[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm².

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.



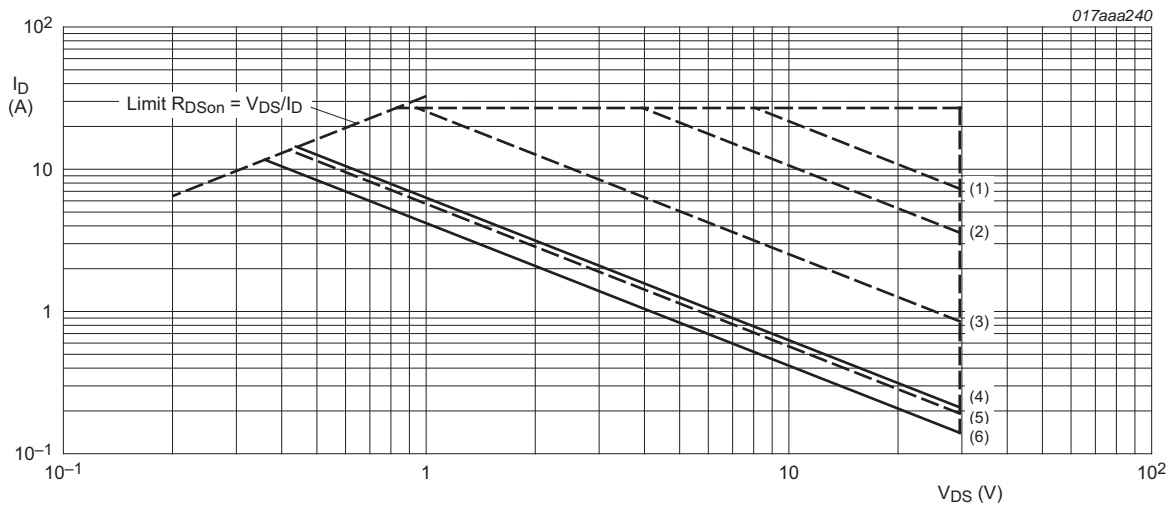
$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}\text{C})}} \times 100 \%$$

Fig 1. Normalized total power dissipation as a function of junction temperature



$$I_{der} = \frac{I_D}{I_{D(25^{\circ}\text{C})}} \times 100 \%$$

Fig 2. Normalized continuous drain current as a function of junction temperature



I_{DM} = single pulse

- (1) $t_p = 100 \mu\text{s}$
- (2) $t_p = 1 \text{ ms}$
- (3) $t_p = 10 \text{ ms}$
- (4) DC; $T_{sp} = 25^{\circ}\text{C}$
- (5) $t_p = 100 \text{ ms}$
- (6) DC; $T_{amb} = 25^{\circ}\text{C}$; drain mounting pad 6 cm^2

Fig 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

6. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit | |
|----------------|--|-------------|-----|-----|-----|------|-----|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1] | - | 198 | 230 | K/W |
| | | | [2] | - | 78 | 90 | K/W |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | | - | 15 | 30 | K/W | |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 6 cm².

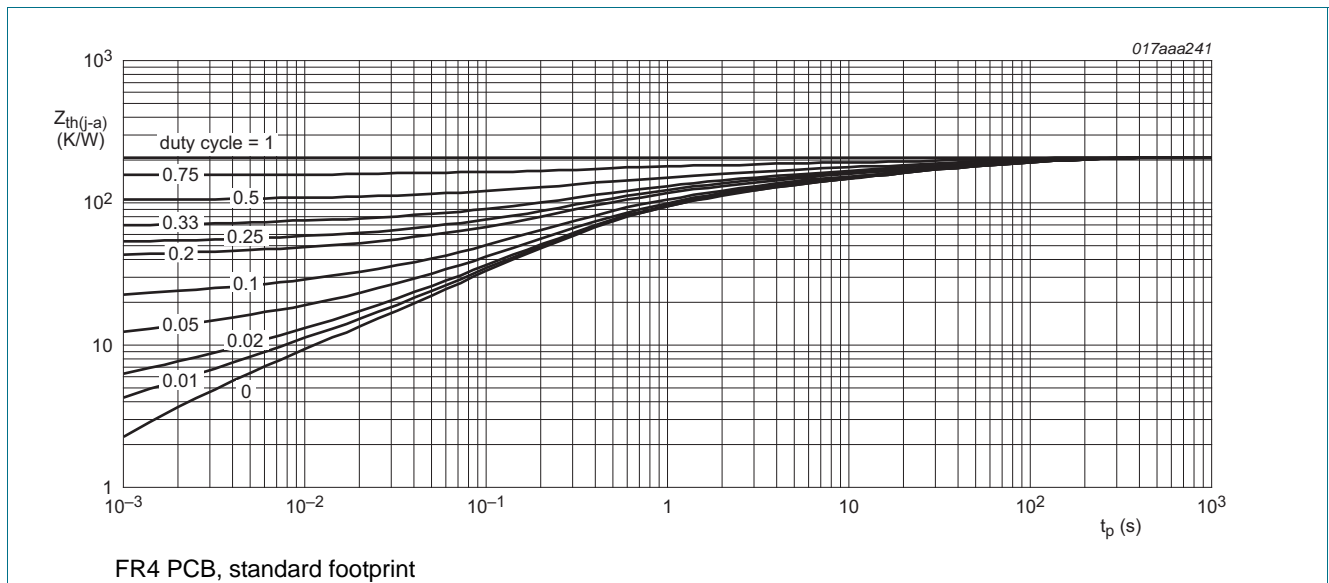


Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

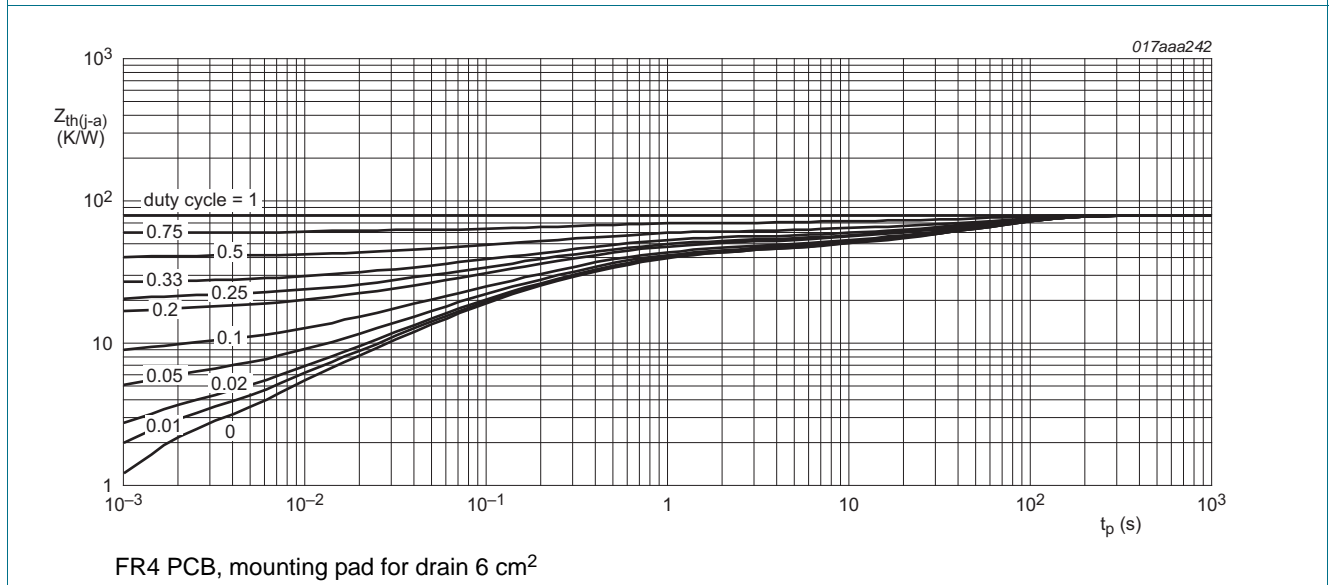


Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

7. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|----------------------------------|--|-----|------|------|---------------|
| Static characteristics | | | | | | |
| $V_{(BR)DSS}$ | drain-source breakdown voltage | $I_D = 250 \mu\text{A}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | 30 | - | - | V |
| V_{GSth} | gate-source threshold voltage | $I_D = 250 \mu\text{A}$; $V_{DS} = V_{GS}$; $T_j = 25 \text{ }^\circ\text{C}$ | 1 | 1.5 | 2.5 | V |
| I_{DSS} | drain leakage current | $V_{DS} = 30 \text{ V}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | - | 1 | μA |
| | | $V_{DS} = 30 \text{ V}$; $V_{GS} = 0 \text{ V}$; $T_j = 150 \text{ }^\circ\text{C}$ | - | - | 10 | μA |
| I_{GSS} | gate leakage current | $V_{GS} = 20 \text{ V}$; $V_{DS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | - | 100 | nA |
| | | $V_{GS} = -20 \text{ V}$; $V_{DS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | - | 100 | nA |
| R_{DSon} | drain-source on-state resistance | $V_{GS} = 10 \text{ V}$; $I_D = 6.7 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | 16 | 20 | m Ω |
| | | $V_{GS} = 10 \text{ V}$; $I_D = 6.7 \text{ A}$; $T_j = 150 \text{ }^\circ\text{C}$ | - | 25 | 31 | m Ω |
| | | $V_{GS} = 4.5 \text{ V}$; $I_D = 4.5 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | 20 | 25 | m Ω |
| g_{fs} | forward transconductance | $V_{DS} = 5 \text{ V}$; $I_D = 3 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | 12 | - | S |
| Dynamic characteristics | | | | | | |
| $Q_{G(tot)}$ | total gate charge | $V_{DS} = 15 \text{ V}$; $I_D = 3 \text{ A}$; $V_{GS} = 10 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | 12.4 | 18.6 | nC |
| Q_{GS} | gate-source charge | | - | 1.7 | - | nC |
| Q_{GD} | gate-drain charge | | - | 2.1 | - | nC |
| C_{iss} | input capacitance | $V_{DS} = 15 \text{ V}$; $f = 1 \text{ MHz}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | 630 | - | pF |
| C_{oss} | output capacitance | | - | 155 | - | pF |
| C_{rss} | reverse transfer capacitance | | - | 70 | - | pF |
| $t_{d(on)}$ | turn-on delay time | $V_{DS} = 15 \text{ V}$; $V_{GS} = 10 \text{ V}$; $R_{G(ext)} = 6 \Omega$; $T_j = 25 \text{ }^\circ\text{C}$; $I_D = 3 \text{ A}$ | - | 4 | - | ns |
| t_r | rise time | | - | 11 | - | ns |
| $t_{d(off)}$ | turn-off delay time | | - | 200 | - | ns |
| t_f | fall time | | - | 85 | - | ns |
| Source-drain diode | | | | | | |
| V_{SD} | source-drain voltage | $I_S = 1.2 \text{ A}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | 0.72 | 1.2 | V |

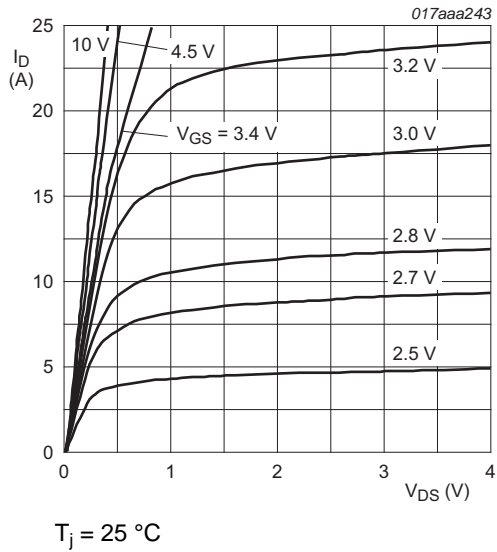


Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values

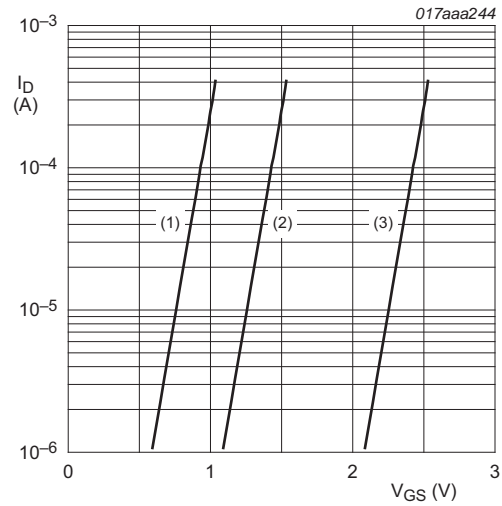


Fig 7. Sub-threshold drain current as a function of gate-source voltage

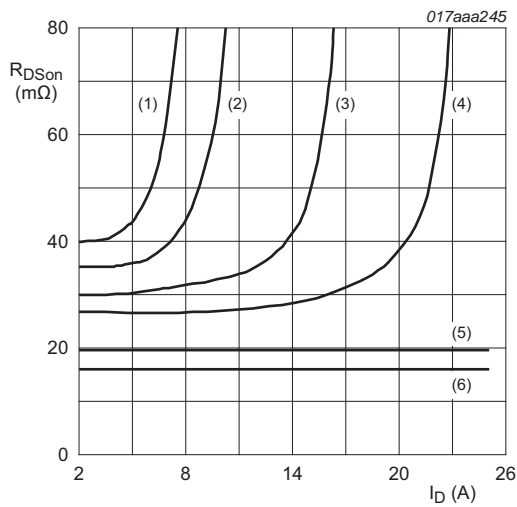


Fig 8. Drain-source on-state resistance as a function of drain current; typical values

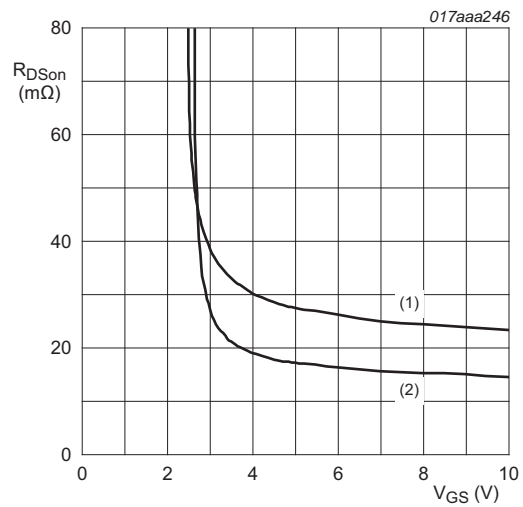
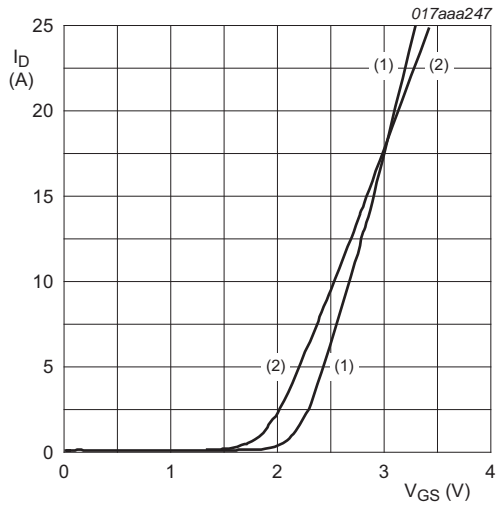
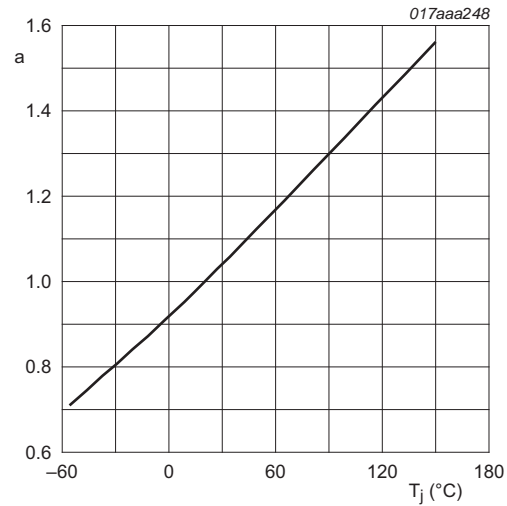


Fig 9. Drain-source on-state resistance as a function of gate-source voltage; typical values



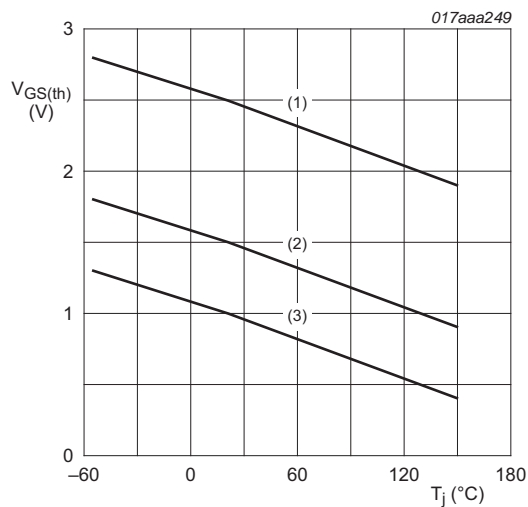
$V_{DS} > I_D \times R_{DS(on)}$
 (1) $T_j = 25\text{ °C}$
 (2) $T_j = 150\text{ °C}$

Fig 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values



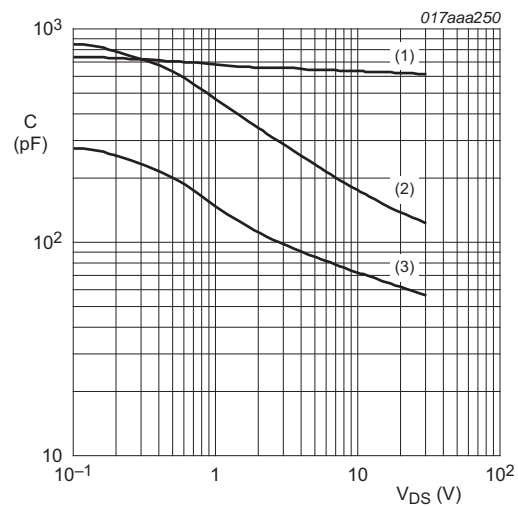
$$a = \frac{R_{DS(on)}}{R_{DS(on)(25^\circ\text{C})}}$$

Fig 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values



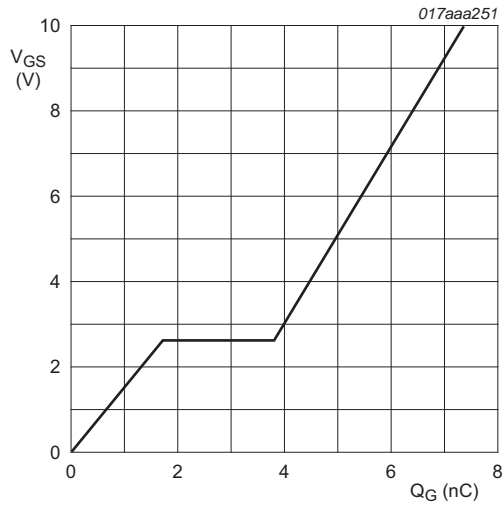
$I_D = 0.25\text{ mA}; V_{DS} = V_{GS}$
 (1) maximum values
 (2) typical values
 (3) minimum values

Fig 12. Gate-source threshold voltage as a function of junction temperature



$f = 1\text{ MHz}; V_{GS} = 0\text{ V}$
 (1) C_{iss}
 (2) C_{oss}
 (3) C_{rss}

Fig 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$I_D = 3 \text{ A}; V_{DS} = 10 \text{ V}; T_{amb} = 25 \text{ }^\circ\text{C}$

Fig 14. Gate-source voltage as a function of gate charge; typical values

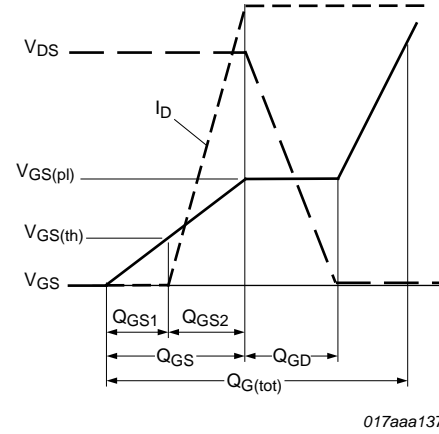
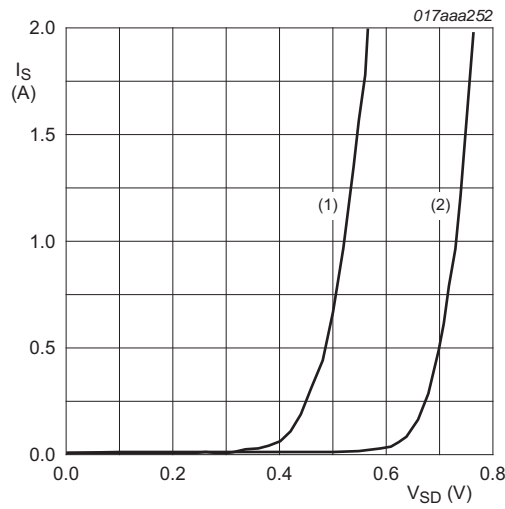


Fig 15. Gate charge waveform definitions



$V_{GS} = 0 \text{ V}$
 (1) $T_j = 150 \text{ }^\circ\text{C}$
 (2) $T_j = 25 \text{ }^\circ\text{C}$

Fig 16. Source current as a function of source-drain voltage; typical values

8. Test information

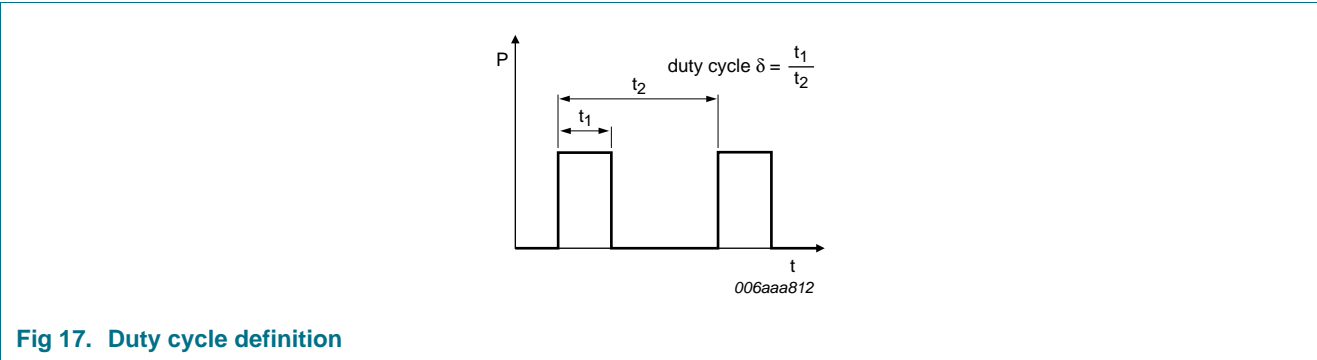


Fig 17. Duty cycle definition

9. Package outline

Plastic surface-mounted package (TSOP6); 6 leads

SOT457

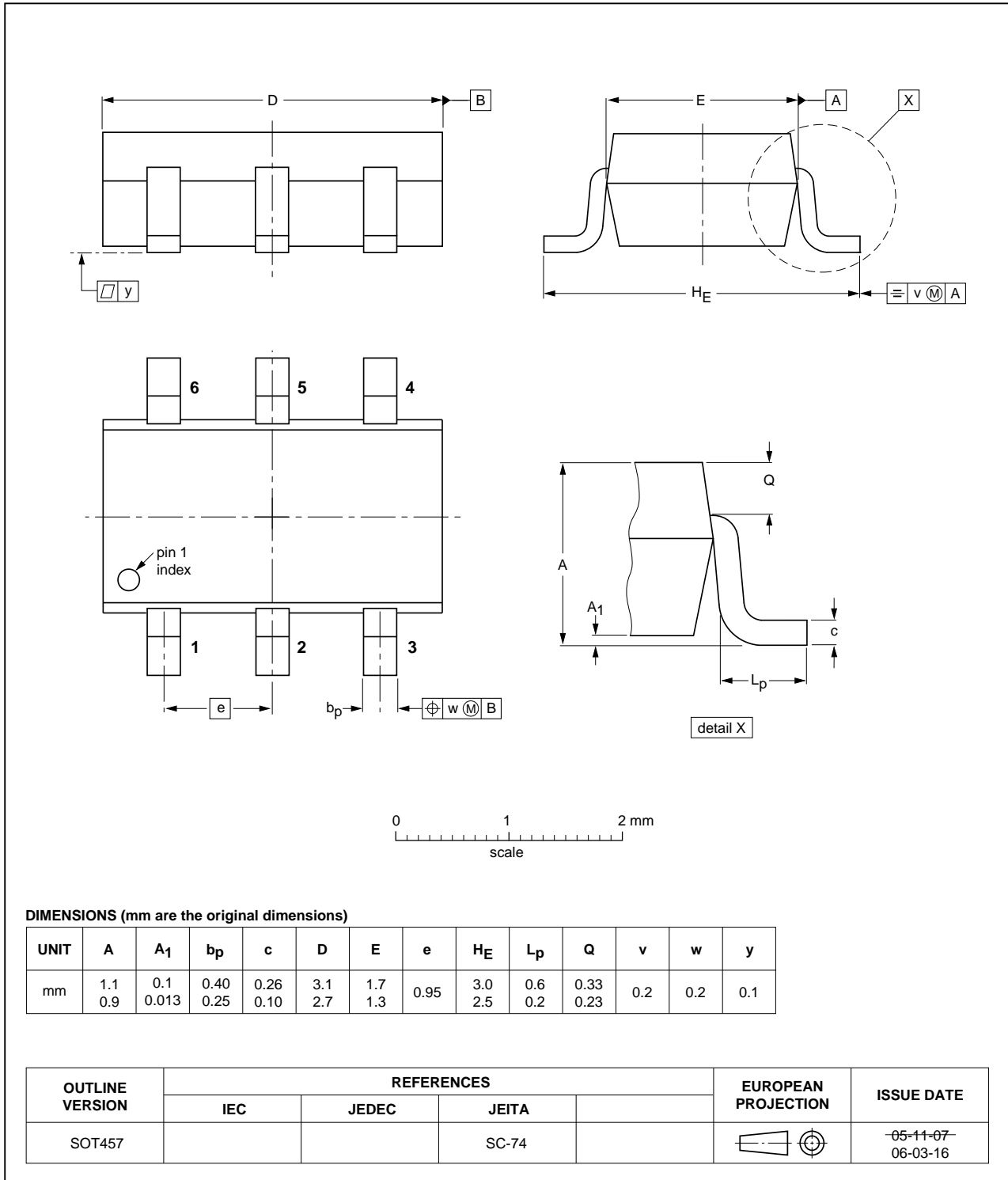


Fig 18. Package outline SOT457 (TSOP6)

10. Soldering

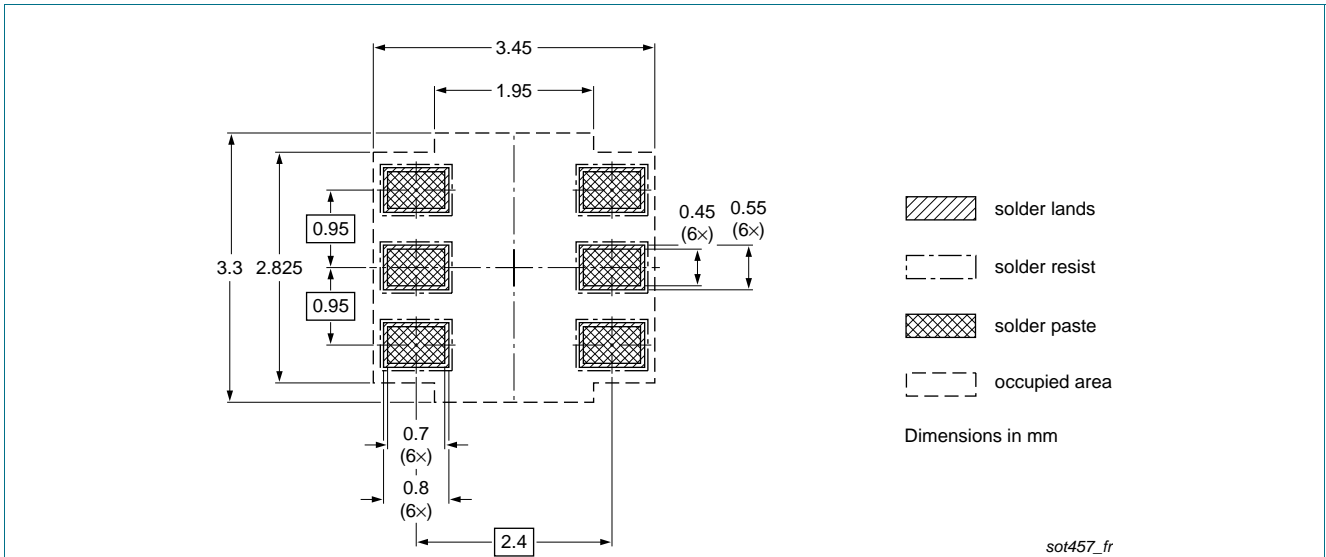


Fig 19. Reflow soldering footprint for SOT457 (TSOP6)

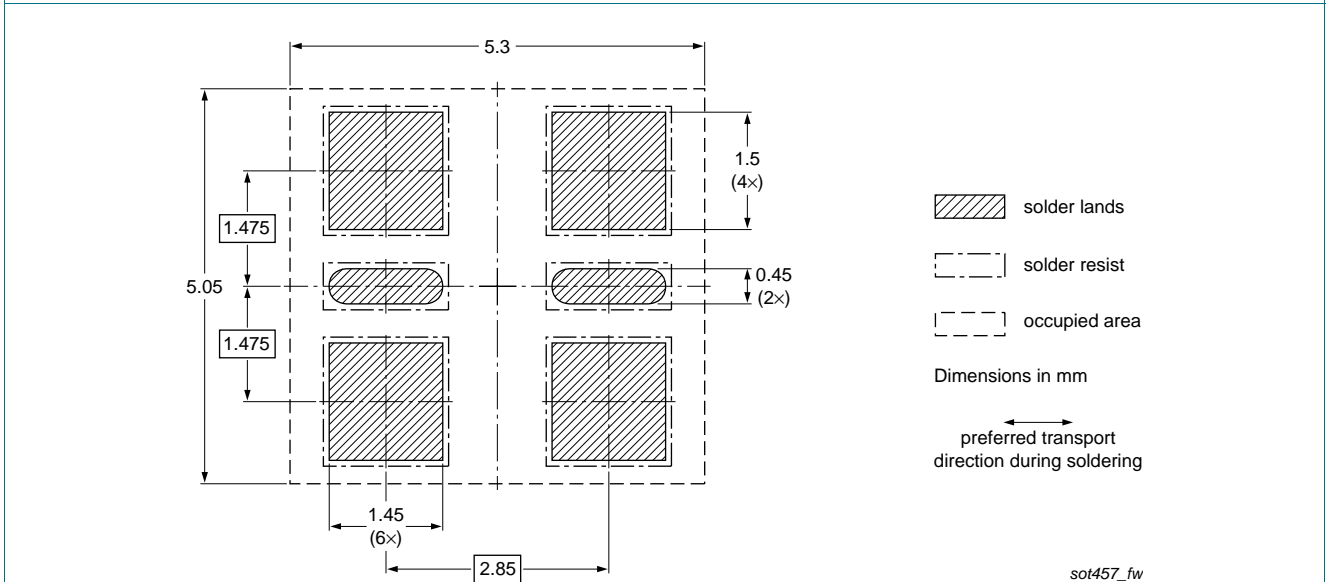


Fig 20. Wave soldering footprint for SOT457 (TSOP6)

11. Revision history

Table 8. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|-------------|--------------|--------------------|---------------|------------|
| PMN20EN v.1 | 20110530 | Product data sheet | - | - |

12. Legal information

12.1 Data sheet status

| Document status ^[1] ^[2] | Product status ^[3] | Definition |
|---|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
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